

Search Results for: 5962-1820501VXC

Current Production Information

TI Part Number:	5962-1820501VXC	Assembly Site:	Ext - Mfg
Lead/Ball Finish:	NiAu	Package Type / Pins:	HKY 34
Planned Lead/Ball Finish:	NiAu	Package Body Size (WxLxH) m	21.49 x 7.62 x 1.53
MSL / Reflow Ratings:	NA	Total Device Mass (mg):	2586.0147

Environmental Ratings Information

RoHS & High-Temp Compliant:	Y	Green Compliant:	Y
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Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Aluminum and Its Alloys	Aluminum	7429-90-5	1.092926	99	990000	0.0423	42
Other Inorganic Materials	Silicon	7440-21-3	0.009527	1	10000	0.0004	0
Sub-Total			1.102452	100	1000000	0.0427	42
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	3.385264	79	790000	0.1309	131
Thermoplastics	Epoxy	85954-11-6	0.899880	21	210000	0.0348	35
Sub-Total			4.285144	100	1000000	0.1657	166
Lid							
Copper and Its Alloys	Fe	7439-89-6	223.141600	53.40	534000	8.6288	8629
Other Nonferrous Metals and Alloys	Co	7440-48-4	68.923300	16.50	165000	2.6652	2665
Nickel and Its Alloys	Ni	7440-02-0	124.220700	29.73	297300	4.8036	4804
Aluminum and Its Alloys	Aluminum	7429-90-5	0.033400	0.01	100	0.0013	1
Other Nonferrous Metals and Alloys	Magnesium	7439-95-4	1.086700	0.26	2600	0.0420	42
Copper and Its Alloys	Copper	7440-50-8	0.418000	0.10	1000	0.0162	16
Sub-Total			417.823700	100.00	1000000	16.1571	16157
Lid Plating							
Other Nonferrous Metals and Alloys	Nickel	7440-02-0	12.150000	47.97	479700	0.4698	470
Precious Metals	Gold	7440-57-5	13.180000	52.03	520300	0.5097	510
Sub-Total			25.330000	100	1000000	0.9795	980
Lid Seal							
Precious Metals	Gold	7440-57-5	24.360000	80.00	800000	0.9420	942
Tin and Its Alloys	Tin	7440-31-5	6.090000	20.00	200000	0.2355	235
Sub-Total			30.450000	100	1000000	1.1775	1177
Semiconductor Device							
Ceramics / Glass	Silicon	7440-21-3	15.520075	100	1000000	0.6002	600
Sub-Total			15.520075	100	1000000	0.6002	600
Header							
Ceramic							
Other Inorganic Materials	Aluminum oxide	1344-28-1	328.848000	90.50	905000	12.7164	12716
Other Inorganic Materials	Silicon dioxide	7631-86-9	12.801000	3.52	35200	0.4950	495
Other Inorganic Materials	calcium oxide	1305-78-8	2.220000	0.61	6100	0.0858	86
Magnesium and Its Alloys	Magnesium oxide	1309-48-4	1.813000	0.50	5000	0.0701	70
Other Inorganic Materials	Titanium dioxide	13463-67-7	3.641000	1.00	10000	0.1408	141
Other Inorganic Materials	Chromium oxide	1308-38-9	14.040000	3.87	38700	0.5429	543
Sub-Total			363.363000	100.00	1000000	14.0510	14051
Metallization							
Other Nonferrous Metals and Alloys	Tungsten	7440-33-7	40.004000	74.50	745000	1.5469	1547

Other Nonferrous Metals and Alloys	molybdenum	7439-98-7	13.390000	25.50	255000	0.5178	518
Sub-Total Leadframe			53.394000	100.00	1000000	2.0647	2065
Copper and Its Alloys	Iron	7439-89-6	159.630000	58.00	580000	6.1728	6173
Nickel and Its Alloys	Nickel	7440-02-0	115.594000	42.00	420000	4.4700	4470
Sub-Total Lead Braze			275.224000	100.00	1000000	10.6428	10643
Precious Metals	Silver	7440-22-4	9.872000	85.00	850000	0.3817	382
Copper and Its Alloys	Copper	7440-50-8	1.742000	15.00	150000	0.0674	67
Sub-Total Heat Sink			11.614000	100.00	1000000	0.4491	449
Copper and Its Alloys	Copper	7440-50-8	127.006000	10.00	100000	4.9113	4911
Other Nonferrous Metals and Alloys	Tungsten	7440-33-7	1143.051000	90.00	900000	44.2013	44201
Sub-Total Heat Sink Braze			1270.057000	100.00	1000000	49.1126	49112
Precious Metals	Silver	7440-22-4	41.020000	72.00	720000	1.5862	1586
Copper and Its Alloys	Copper	7440-50-8	15.951000	28.00	280000	0.6168	617
Sub-Total HEAT SINK Plating			56.971000	100.00	1000000	2.203	2203
Nickel and Its Alloys	Nickel	7440-02-0	1.860000	100.00	1000000	0.0719	72
Sub-Total HEAT SINK Plating			1.860000	100.00	1000000	0.0719	72
Nickel and Its Alloys	Nickel	7440-02-0	5.078000	90.95	909500	0.1964	196
Copper and Its Alloys	Phosphorous	7723-14-0 *1	0.502000	8.99	89900	0.0194	19
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.003400	0.06	600	0.0001	0
Sub-Total Plating			5.583400	100.00	1000000	0.2159	215
Precious Metals	Palladium	7440-05-3	0.152000	7.45	74500	0.0059	6
Nickel and Its Alloys	Nickel	7440-02-0	1.874000	91.87	918700	0.0725	72
Other Nonferrous Metals and Alloys	Boron	7440-42-8	0.013000	0.64	6400	0.0005	1
Other Nonferrous Metals and Alloys	Lead	7439-92-1	0.000940	0.04	400	0.0000	0
Sub-Total Plating			2.039940	100.00	1000000	0.0789	79
Nickel and Its Alloys	Nickel	7440-02-0	15.574000	92.00	920000	0.6022	602
Precious Metals	Cobalt	7440-48-4	1.354000	8.00	80000	0.0524	52
Sub-Total Plating			16.928000	100.00	1000000	0.6546	655
Precious Metals	Gold	7440-57-5	34.469000	100.00	1000000	1.3329	1333
Sub-Total Total			34.469000	100.00	1000000	1.3329	1333
			2586.0147			100.0000	1000000

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Product Content Methodology

[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

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JIG Level-A Banned Substances	Threshold, Homogeneous Level (1)
Asbestos	Not intentionally added
Azo colorants	Not intentionally added
RoHS - Cadmium/Cadmium Compounds	75 ppm, Not intentionally added (RoHS threshold = 100ppm)
RoHS - Hexavalent Chromium/Hex.Chromium.Compounds	1000 ppm, Not intentionally added
RoHS - Lead/Lead Compounds	1000 ppm, Not intentionally added
RoHS - Mercury/Mercury Compounds	1000 ppm, Not intentionally added
Ozone Depleting Substances	Class I : Not intentionally added Class II : 1000ppm
RoHS - Polybrominated Biphenyls (PBBs)	1000 ppm, Not intentionally added
RoHS - Polybrominated Diphenyl Ethers (PBDEs)	1000 ppm, Not intentionally added
Polychlorinated Biphenyls (PCBs)	Not intentionally added
Polychlorinated Naphthalenes (>3 Chlorine atoms)	Not intentionally added
Radioactive Substances	Not intentionally added
Shortchain Chlorinated Paraffins	Not intentionally added
Tributyl Tin (TBT) and Triphenyl Tin (TPT)	Not intentionally added
Tributyl Tin Oxide (TBTO)	Not intentionally added

(1) Threshold does not apply to applications covered by a RoHS substance exemption.

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Name/Title: Hubie Payne, Vice President, Worldwide Quality

Date: August 5, 2019

Common TI Product Stewardship Position Statements

Topic	Download Document
REACH	REACH
RoHS	RoHS Material Declaration Certificate
Lead-free Conversion overview	Materials Content Search Tool
Lead-free (Pb-free) Logo	RoHS Exemption Renewal Process & Exemptions Used by TI
Green Conversion and Low Halogen	Low Halogen
EVM Position Statement	EVM Statement
Cobalt Dichloride	Cobalt Dichloride
Decabromodiphenyl ether (DecaBDE)	DecaBDE
Dimethyl Fumarate (DMF):	DMF
EU ELV	N/A
Ozone Depleting Substances (ODS):	ODS
Perfluorooctane sulfonates (PFOS):	PFOS
HBCDD & Phthalates	HBCDD & Phthalates Statement
Red Phosphorous	Red Phosphorous
Silicone	Silicone Statement

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